

NS1081/NS1081S/NS1081Q

Datasheet

USB 3.0 Flash Card Controller

Revision 1.4

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1. Introduction

NS1081/NS1081S/NS1081Q is a high-performance USB 3.0 Flash Card controller. On one side, it connects with the USB interface and is compatible with USB SuperSpeed (5Gbps), Hi-Speed (480Mbps), and Full-Speed (12Mbps). On the other side, it interfaces with various flash memories, such as Secure Digital (SD), SDHC, SDXC, miniSD, microSD (T-Flash), MultiMediaCard (MMC), Embedded-MultiMediaCard (eMMC), RS-MMC, MMCmicro, or MMCmobile. It also supports high density memory cards with capacity up to 2TB, and high speed memory cards including SD3.0 UHS-I cards and eMMC4.5 HS200.

1.1. Highlights

NS1081/NS1081S/NS1081Q integrates self-developed high-performance USB 3.0 transceivers with low-power and low-jitter. The transceivers have built-in test capabilities for guaranteed functions and performance. The IC also integrates high-efficiency regulators, such as 5V to 1.2V DC-DC regulator and 5V to 3.3V/1.8V LDO regulator.

To increase the memory card capacity and data access rate, NS1081 is capable to support 2-channel RAID0 operation, and NS1081Q is capable to support 4-channel RAID0 operation. These innovations are patent pending.

Both NS1081 and NS1081Q are available in 6x6 QFN 48 pin package. NS1081S only supports single-channel memory card. It is available in either 6x6 QFN 48 pin package, which is pin-to-pin compatible to NS1081; or 5x5 QFN 32 pin package, which is used to save the PCB space.

1.2. Features

- Support USB 3.0 Specification Revision 1.0.
- USB 3.0 adaptive receiver equalization for better and reliable Super-Speed operation.
- Support USB Specification Revision 2.0.
- Support USB Mass Storage Class, Bulk-Only Transport Specification.
- Support USB 3.0 U0/U1/U2/U3 (P0/P1/P2/P3) and USB 2.0 L0/L1/L2 power saving modes.
- Support Secure Digital v1.0/v1.1/v2.0 SDHC/SDXC (Capacity up to 2TB).
- Support Secure Digital v3.0 UHS-I (Ultra High Speed): SDR12/SDR25/SDR50/DDR50/SDR104.
- Support MultiMediaCard (MMC) and Embedded MultiMediaCard (eMMC) specification v4.41/v4.5 x1/x4/x8 bit data bus and DDR x4/x8 bit data transfer mode.
- Support Embedded MultiMediaCard (eMMC) specification v4.5 HS200 data transfer mode.
- Built-in variable sampling clock generator to determine correct sampling point for SD UHS card SDR104 mode and eMMC HS200 mode.
- Support user data locking, providing a privacy protection solution.
- Support SD Lock/Unlock Function.
- 25MHz external crystal.
- Support SPI and I2C interface for firmware and Vendor VID/PID customization.
- On-chip high efficiency 5V to 1.2V DC-DC regulator.
- On-chip 5V to 3.3V and 1.8V regulators.
- External Serial Flash memory interface.
- Support ISP (In System Programming) for firmware upgrade to external SPI Flash or I2C EEPROM via USB port.
- On-chip power MOSFETs for supplying flash media card power.
- Support Win8/ Win7/Vista/XP/2000/Me, Linux and Mac OS 9.x/10.x.
- Support two dedicated LED controllers.
- Package available in 48 pin 6x6 (Rohs) QFN or 32 pin 5x5 (Rohs) QFN.

2. Pin Locations and Descriptions

2.1. NS1081 Package Diagram with Pin Locations

Figure 1 shows the NS1081 pinout from the top of the package.

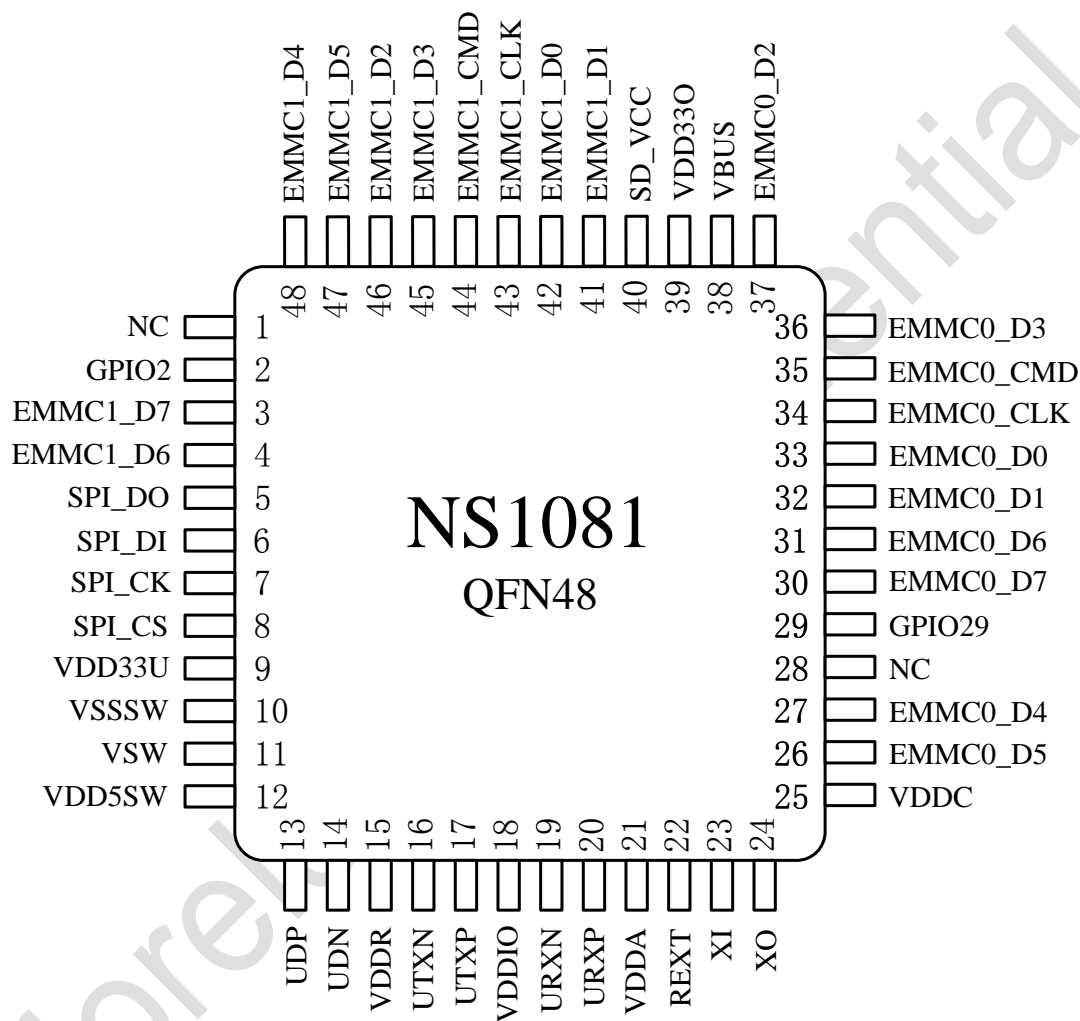


Figure 1. NS1081 48pin QFN package pinout

2.2. NS1081S Package Diagram with Pin Locations

Figure 2 shows the NS1081S 48pin package pinout from the top of the package.

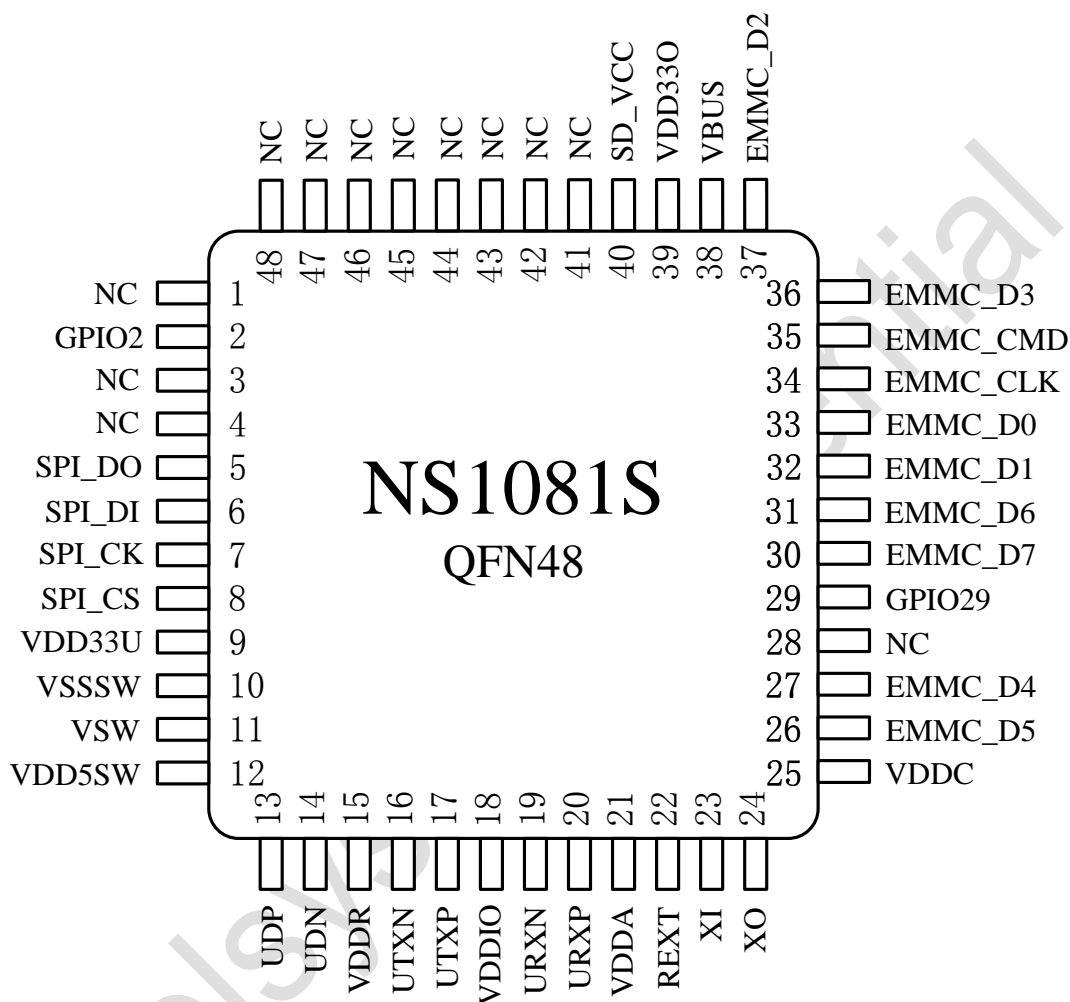


Figure 2. NS1081S 48pin QFN package pinout

Figure 3 shows the NS1081S 32pin package pinout from the top of the package.

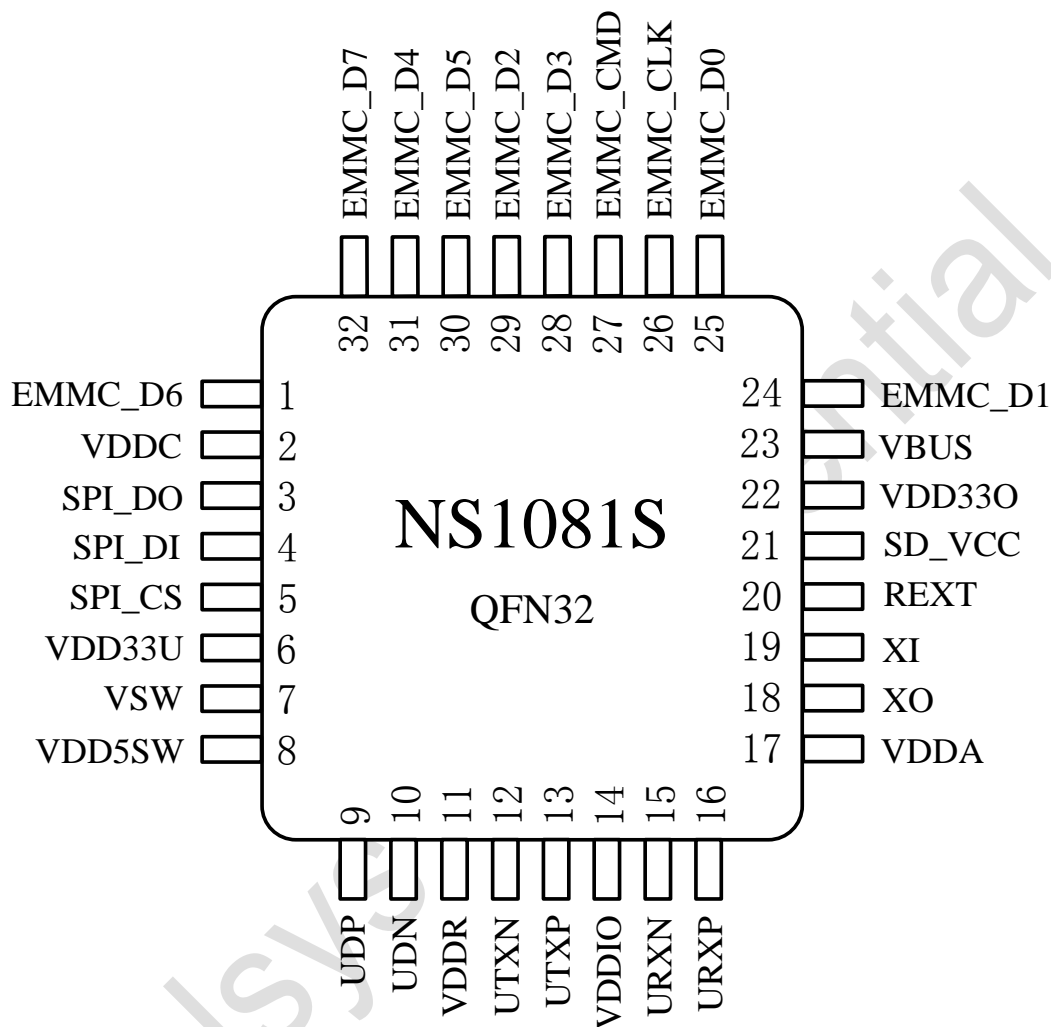


Figure 3. NS1081S 32pin QFN package pinout

2.3. NS1081Q Package Diagram with Pin Locations

Figure 4 shows the NS1081Q pinout from the top of the package.

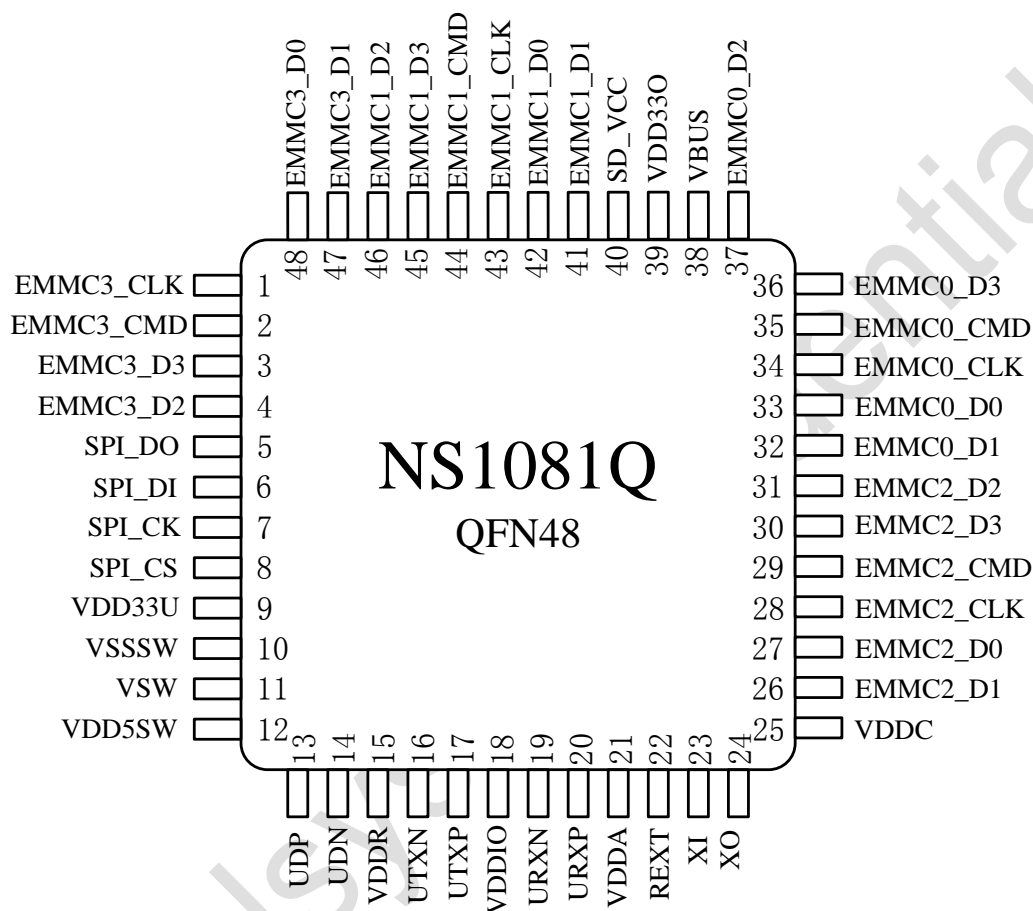


Figure 4. NS1081Q 48pin QFN package pinout

2.4. Pin Definitions

This section provides a detailed description of each signal. The signal type is shown in Table 1. Table 2 shows the detailed pin descriptions of both NS1081 and NS1081S. Table 3 shows the detailed pin description of NS1081Q.

Table 1. Pin Type Description

Type	Description
I	Input
O	Output
I/O	Input/output
PH	Pull high resistor
PL	Pull low resistor
P	Power Supply
G	Ground

Table 2. Pin Descriptions of NS1081 and NS1081S

Signal Name	Pin Number			Type	Description
	NS1081	NS1081S (QFN48)	NS1081S (QFN32)		
USB3.0 Interface					
URXP	20	20	16	I	USB3.0 RX+ Signal
URXN	19	19	15	I	USB3.0 RX- Signal
UTXP	17	17	13	O	USB3.0 TX+ Signal A 100nFcapacitor should be connected between this pin and USB connector.
UTXN	16	16	12	O	USB3.0 TX- Signal A 100nF capacitor should be connected between this pin and USB connector.
USB2.0 Interface					
UDN	14	14	10	I/O	USB2.0 Bus D- Signal
UDP	13	13	9	I/O	USB2.0 Bus D+ Signal
VBUS	38	38	23	I	USB Cable Power Detector.
Flash Card Interface					
EMMC0_CLK	34	34	-	O	EMMC0 clock output.
EMMC0_CMD	35	35	-	IO	EMMC0 command and response
EMMC0_D0	33	33	-	IO	EMMC0 data bit0

Pin Descriptions of NS1081 and NS1081S (continued)

EMMC0_D1	32	32	-	IO	EMMC0 data bit1
EMMC0_D2	37	37	-	IO	EMMC0 data bit2
EMMC0_D3	36	36	-	IO	EMMC0 data bit3
EMMC0_D4	27	27	-	IO	EMMC0 data bit4
EMMC0_D5	26	26	-	IO	EMMC0 data bit5
EMMC0_D6	31	31	-	IO	EMMC0 data bit6
EMMC0_D7	30	30	-	IO	EMMC0 data bit7
EMMC1_CLK	43	-	26	O	EMMC1 clock output.
EMMC1_CMD	44	-	27	IO	EMMC1 command and response
EMMC1_D0	42	-	25	IO	EMMC1 data bit0
EMMC1_D1	41	-	24	IO	EMMC1 data bit1
EMMC1_D2	46	-	29	IO	EMMC1 data bit2
EMMC1_D3	45	-	28	IO	EMMC1 data bit3
EMMC1_D4	48	-	31	IO	EMMC1 data bit4
EMMC1_D5	47	-	30	IO	EMMC1 data bit5
EMMC1_D6	4	-	1	IO	EMMC1 data bit6
EMMC1_D7	3	-	32	IO	EMMC1 data bit7
Crystal Interface					
XI	23	23	19	I	Crystal Input/Oscillator Input. This pin should be connected to a 25MHz crystal or crystal oscillator.
XO	24	24	18	O	Crystal Output. If a crystal oscillator connected to XI, XO must be left open.
Control and GPIO Interface					
SPI_DO	5	5	3	IO	SPI data output / I2C data
SPI_DI	6	6	4	IO	SPI data input / LED0
SPI_CK	7	7	-	IO	SPI clock output / I2C clock / LED1
SPI_CS	8	8	5	IO	SPI active-low enable
REXT	22	22	20	I	511 $\Omega \pm 1\%$ external reference resistor connected between this pin and VDDIO.
GPIO2	2	2	-	IO	GPIO2
GPIO29	29	29	-	IO	GPIO29
Power and Ground					
VDDA	21	21	17	P	1.2V Analog Power Supply.
VDDR	15	15	11	P	1.2V Digital Power Supply.
VDDC	25	25	2	P	1.2V Core Logic Power Supply.

Pin Descriptions of NS1081 and NS1081S (continued)

VDDIO	18	18	14	P	1.2V I/O Power Supply.
VDD33U	9	9	6	P	3.3V USB2.0 Power Supply.
VDD33O	39	39	22	P	3.3V voltage LDO output.
SD_VCC	40	40	21	P	3.3V card power output.
VDD5SW	12	12	8	P	5V voltage regulator Power Supply.
VSW	11	11	7	P	1.2V voltage regulator output.
VSSSW	10	10	-	G	Voltage regulator Ground.

Table 3. Pin Description of NS1081Q

Signal Name	Pin Number	Type	Description
USB3.0 Interface			
URXP	20	I	USB3.0 RX+ Signal
URXN	19	I	USB3.0 RX- Signal
UTXP	17	O	USB3.0 TX+ Signal. A 100nF capacitor should be connected between this pin and USB connector.
UTXN	16	O	USB3.0 TX- Signal. A 100nF capacitor should be connected between this pin and USB connector.
USB2.0 Interface			
UDN	14	I/O	USB2.0 Bus D- Signal
UDP	13	I/O	USB2.0 Bus D+ Signal
VBUS	38	I	USB Cable Power Detector.
Flash Card Interface			
EMMC3_CLK	1	O	EMMC3 clock output.
EMMC3_CMD	2	IO	EMMC3 command and response
EMMC3_D3	3	IO	EMMC3 data bit3
EMMC3_D2	4	IO	EMMC3 data bit2
EMMC3_D1	47	IO	EMMC3 data bit1
EMMC3_D0	48	IO	EMMC3 data bit0
EMMC2_CLK	28	O	EMMC2 clock output.
EMMC2_CMD	29	IO	EMMC2 command and response
EMMC2_D3	30	IO	EMMC2 data bit3
EMMC2_D2	31	IO	EMMC2 data bit2
EMMC2_D1	26	IO	EMMC2 data bit1
EMMC2_D0	27	IO	EMMC2 data bit0

Pin Description of NS1081Q (continued)

EMMC1_CLK	43	O	EMMC1 clock output.
EMMC1_CMD	44	IO	EMMC1 command and response
EMMC1_D3	45	IO	EMMC1 data bit3
EMMC1_D2	46	IO	EMMC1 data bit2
EMMC1_D1	41	IO	EMMC1 data bit1
EMMC1_D0	42	IO	EMMC1 data bit0
EMMC0_CLK	34	O	EMMC0 clock output.
EMMC0_CMD	35	IO	EMMC0 command and response
EMMC0_D3	36	IO	EMMC0 data bit3
EMMC0_D2	37	IO	EMMC0 data bit2
EMMC0_D1	32	IO	EMMC0 data bit1
EMMC0_D0	33	IO	EMMC0 data bit0
Crystal Interface			
XI	23	I	Crystal Input/Oscillator Input. This pin should be connected to a 25MHz crystal or crystal oscillator.
XO	24	O	Crystal Output. If a crystal oscillator connected to XI, XO must be left open.
Control and GPIO Interface			
SPI_DO	5	IO	SPI data output / I2C data
SPI_DI	6	IO	SPI data input / LED0
SPI_CK	7	IO	SPI clock output / I2C clock / LED1
SPI_CS	8	IO	SPI active-low enable
REXT	22	I	511 $\Omega \pm 1\%$ external reference resistor connected between this pin and VDDIO.
Power and Ground			
VDDA	21	P	1.2V Analog Power Supply.
VDDR	15	P	1.2V Digital Power Supply.
VDDC	25	P	1.2V Core Logic Power Supply.
VDDIO	18	P	1.2V I/O Power Supply.
VDD33U	9	P	3.3V USB2.0 Power Supply.
VDD33O	39	P	3.3V voltage LDO output.
SD_VCC	40	P	3.3V card power output.
VDD5SW	12	P	5V voltage regulator Power Supply.
VSW	11	P	1.2V voltage regulator output.
VSSSW	10	G	Voltage regulator Ground.

3. Block Diagram and Descriptions

3.1. Block Diagram

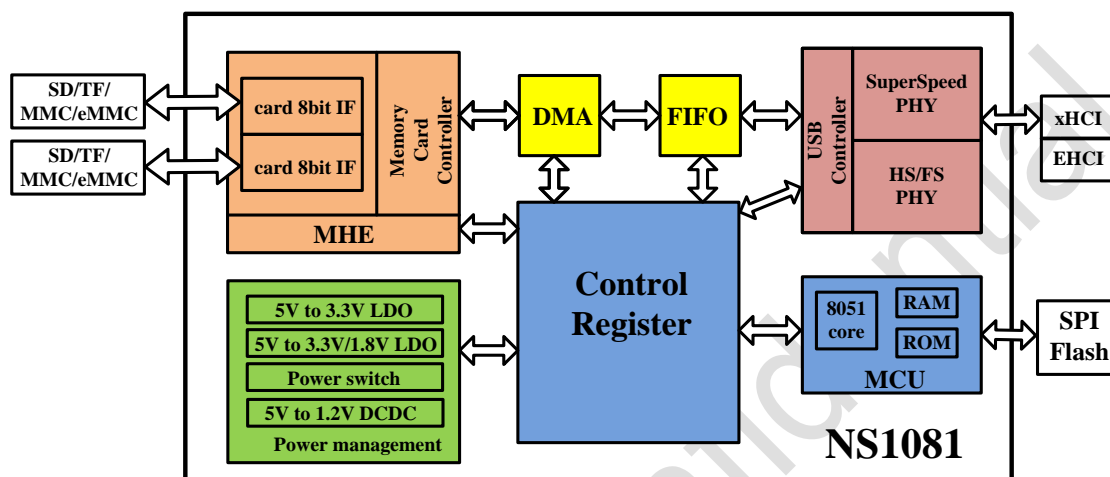


Figure 5. NS1081 Functional Block Diagram

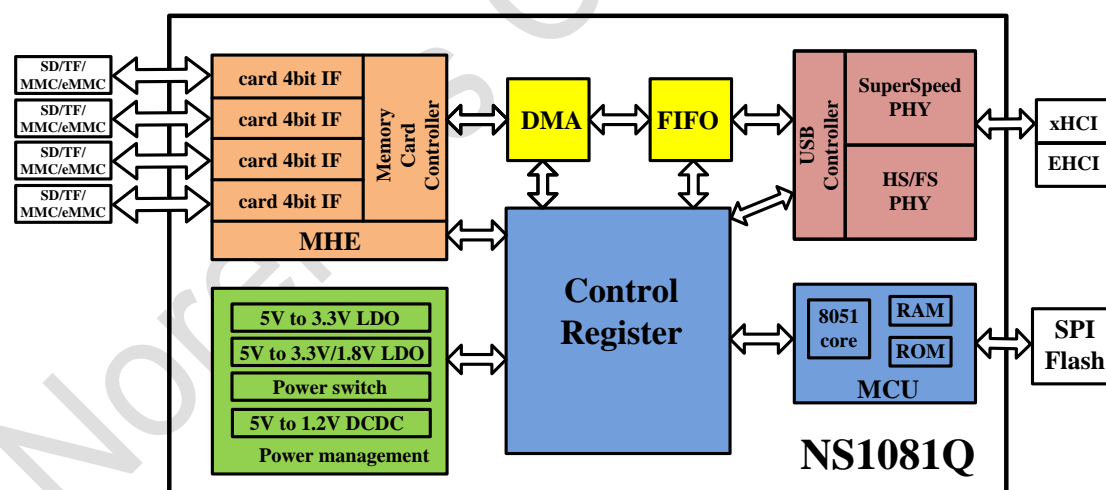


Figure 6. NS1081Q Functional Block Diagram

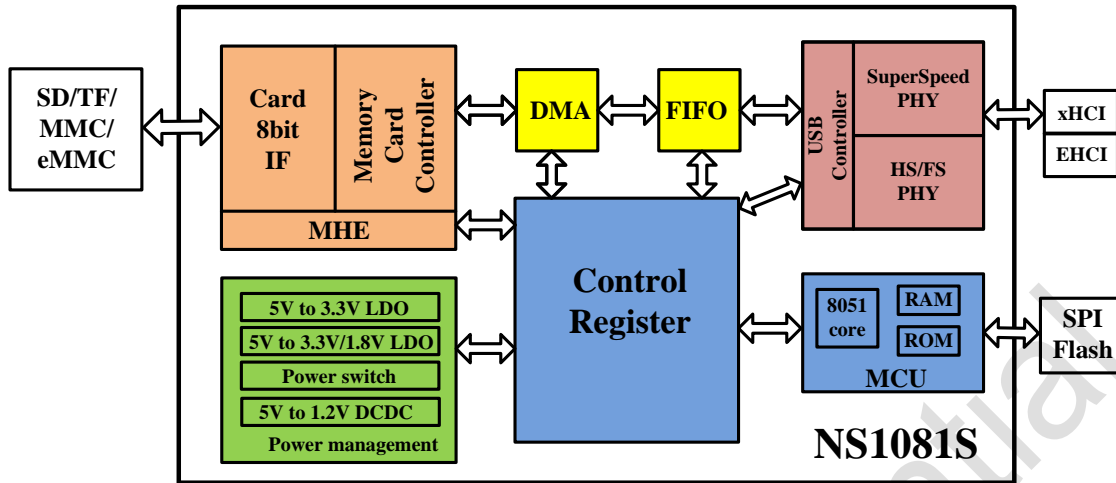


Figure 7. NS1081S Functional Block Diagram

3.2. Descriptions

■ SuperSpeed and HS/FS PHY

The SuperSpeed and HS/FS PHY contains the transmitter and receiver analog circuitry that handles the low level USB protocol and signaling. The transceivers have built-in test capabilities for guaranteed functions and performance. It also has the function of adaptive receiver equalization for better and reliable Super-Speed operation.

■ USB Controller

The usb controller, which contains the logic to handle link layer and protocol layer functions. It also contains various state machines to manage usb packets and transactions.

■ MHE (Media Hardware Engine)

Media Interface compatible with SD/TF/MMC/eMMC. It also has the analog circuitry to support both the SDR and DDR data transfer modes.

■ MCU

- **8051 Core** A fast 8-bit microcontroller which executes ASM51 instruction set.
- **ROM** Firmware code on ROM.
- **RAM** Program RAM and Data RAM for 8051 Core.

■ DMA

The DMA module is integrated in the usb controller and memory card controller. It is used to transfer large chunks of data without MCU intervention. The transfer type and length are configurable.

■ FIFO

The FIFO is designed to provide a simple and powerful interface to the on-chip buffer memory for USB controller and memory card controller.

■ Power Management

5V to 3.3V LDO: current capability 500mA

5V to 1.2V DCDC: high-efficiency PWM and PFM for active and suspend mode, respectively

5V to 3.3V/1.8V LDO: card IO power, support suspend mode

Power switch: support card power off

4. Electrical Characteristics

4.1. Absolute Maximum Ratings

Table 4. Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
VDDA/VDDR/VDDC /VDDIO	1.2V supply voltage	-0.3 to 1.54	V
VDD33O/VDD33U	3.3V supply voltage	-0.3 to 4.0	V
VDD5SW	5V supply voltage	-0.3 to 5.5	V
Storage temperature	T _{STORAGE}	-40 to 150	°C

4.2. Recommended Operating Conditions

Table 5. Recommended Operating Conditions

Symbol	Parameter	Min	Type	Max	Unit
VDDA/VDDR/VDDC /VDDIO	1.2V supply voltage	1.14	1.2	1.35	V
VDD33O/VDD33U	3.3V supply voltage	3.0	3.3	3.6	V
VDD5SW	5V supply voltage	4.5	5	5.5	V
T _A	Operating free-air temperature range	0	-	95	°C
T _J	Operating junction temperature range	-40	-	125	°C

4.3. Reference Clock Requirement

Table 6. Reference Clock Requirement

Parameter	Min	Type	Max	Unit
Crystal frequency	-	25	-	MHz
Clock Duty Cycle	45	50	55	%
Clock frequency accuracy	-300		300	ppm

4.4. DC Characteristics for Digital IO

Table 7. DC Characteristics for Digital IO

Symbol	Parameter	Min	Type	Max	Unit
V_{IH}	Input High Level	2.0	-	3.6	V
V_{IL}	Input Low Level	-	-	0.8	V
V_{OH}	Output High Level	2.4	-	-	V
V_{OL}	Output Low Level	-	-	0.5	V
I_{ACTIVE}	Super Speed Mode		132		mA
	High-Speed Mode		55.0		mA
$I_{SUSPEND}$	Super Speed Mode		1.53		mA
	High-Speed Mode		1.66		mA

4.5. Power Up and Reset Timing

The Power Up and Reset Timing rules are defined in this section. Designers should follow all the rules for external power designs. Detailed explanations are listed as Figure 8.

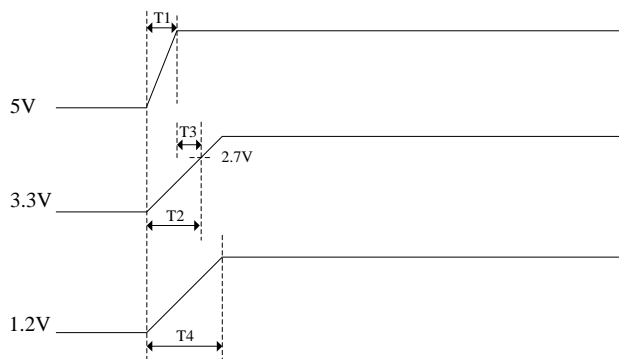


Figure 8. Power Up and Reset Timing

T1: Rise time for 5V power rail form 0V to 5V

T2: Rise time for 3.3V power rail form 0V to 2.7V

T3: Delay from the time when 5V power is ready to the time when 3.3V power supply voltage reaches 2.7V.

T4: Rise time for 1.2V power rail form 0V to 1.2V

The recommended power sequence and timing requirements are listed as Table 8.

Table 8. Power Up and Reset Timing Requirement

Time	Min	Max
T1	0.01ms	1ms
T2	0.01ms	1ms
T3	0.01ms	0.2ms
T4	0.01ms	1ms

5. Package Information

5.1. 48 pin QFN (6x6) package

Figure 9. 48 pin QFN package outline

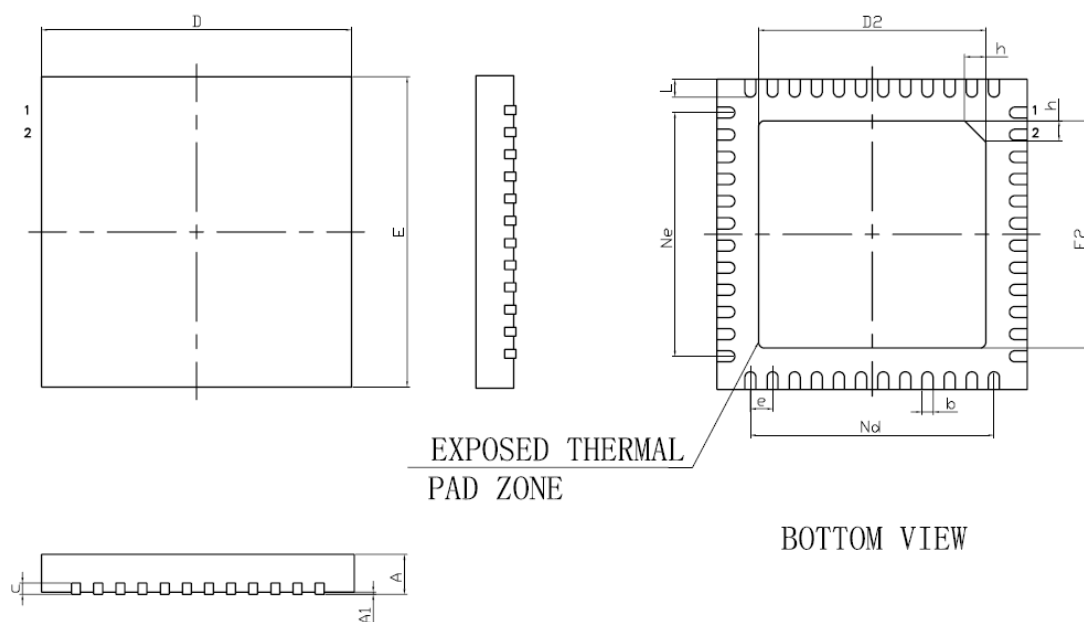


Table 9. 48 pin QFN package mechanical data

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	—	0.02	0.05
b	0.15	0.20	0.25
c	0.18	0.20	0.23
D	5.90	6.00	6.10
D2	4.10	4.20	4.30
e	0.40BSC		
Ne	4.40BSC		
Nd	4.40BSC		
E	5.90	6.00	6.10
E2	4.10	4.20	4.30
L	0.35	0.40	0.45
h	0.30	0.35	0.40
L/P载体尺寸 (MIL)	177*177		

5.2. 32 pin QFN (5x5) package

Figure 10. 32 pin QFN package outline

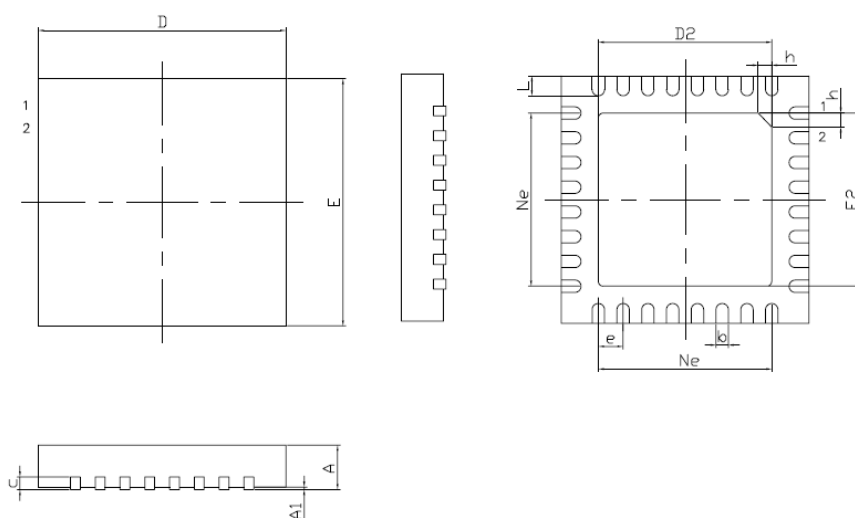


Table 10. 32 pin QFN package mechanical data

SYMBOL	MILLIMETER	
	MIN	MAX
A	0.70	0.80
A1	—	0.05
b	0.18	0.30
c	0.18	0.25
D	4.90	5.10
D2	3.40	3.60
e	0.50BSC	
Ne	3.50BSC	
E	4.90	5.10
E2	3.40	3.60
L	0.35	0.45
h	0.30	0.40